

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ERIC BOHANNON	12/23/2020
RECEIVING PARTY DATA	
Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
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State/Country:	JAPAN
Postal Code:	243-0014
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17122249
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NAME OF SUBMITTER:	CHRISTOPHER M. TOBIN
SIGNATURE:	/Christopher M. Tobin/
DATE SIGNED:	02/02/2021
Total Attachments: 2	
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ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred to as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to **Sony Semiconductor Solutions Corporation** located and doing business at **4-14-1 Asahicho, Atsugi-shi, Kanagawa, 243-0014 Japan** ("ASSIGNEE") for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the U.S. provisional application, non-provisional application, or national phase application entitled "**DIGITALLY-CALIBRATED CTIA IMAGE SENSOR PIXEL**", bearing the U.S. Application Serial No. **17/122,249**, filed on **December 15, 2020** ("APPLICATION"); and

2. The entire worldwide right, title, and interest in and to:
(a) the APPLICATION; (b) all applications claiming priority from the APPLICATION; (c) all utility, divisional, continuation, substitute, renewal, reissue, and other related applications thereto which have been or may be filed in the United States or elsewhere in the world; (d) all patents (including reissues and re-examinations) which may be granted on the applications set forth in (a), (b), (c) and
(d) above; and (e) all right of priority in the APPLICATION, together with all rights to recover damages for infringement of provisional rights.

INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all oaths, assignments, powers of attorney, applications, and other papers necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.

INVENTOR represents that INVENTOR has the rights, titles, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has not made and will not hereafter make any assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR grants the attorney(s) of record in this application the power to inspect the U.S. Application Serial No. and filing date of the Application in the spaces provided above.

This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment.

This Assignment is executed on the date(s) indicated below.

Eric Bohannon
Name of first inventor

San Diego, California, USA
Residence of first inventor

Eric Bohannon
Signature of first inventor

Date Jan 21, 2021